

Features

- Very high speed: 55 ns
- Wide voltage range: 2.20 V–3.60 V
- Ultra-low active power
 - Typical active current: 2 mA @ f = 1 MHz
 - Typical active current: 15 mA @ f = f_{max}
- Ultra low standby power
- Easy memory expansion with \overline{CE}_1 , CE₂ and \overline{OE} features
- Automatic power-down when deselected
- Complementary metal oxide semiconductor (CMOS) for optimum speed/power
- Packages offered in a 48-ball fine ball grid array (FBGA)

Functional Description^[1]

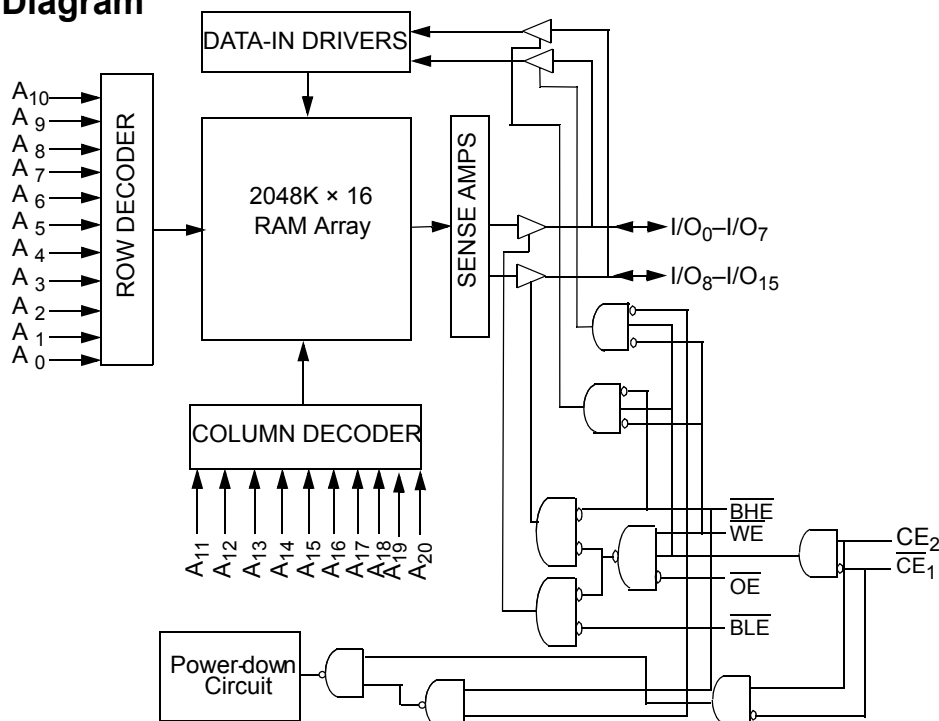
The CY62177DV30 is a high-performance CMOS static RAM organized as 2M words by 16 bits. This device features advanced circuit design to provide ultra-low active current. This is ideal for providing More Battery Life™ (MoBL®) in portable

applications such as cellular telephones. The device also has an automatic power-down feature that significantly reduces power consumption. The device can also be put into standby mode when deselected (\overline{CE}_1 HIGH or CE₂ LOW or both BHE and BLE are HIGH). The input/output pins (I/O₀ through I/O₁₅) are placed in a high-impedance state when: deselected (\overline{CE}_1 HIGH or CE₂ LOW), outputs are disabled (\overline{OE} HIGH), both Byte High Enable and Byte Low Enable are disabled (BHE, BLE HIGH), or during a write operation (CE₁ LOW, CE₂ HIGH and WE LOW).

Writing to the device is accomplished by taking Chip Enables (CE₁ LOW and CE₂ HIGH) and Write Enable (WE) input LOW. If Byte Low Enable (\overline{BLE}) is LOW, then data from I/O pins (I/O₀ through I/O₇), is written into the location specified on the address pins (A₀ through A₂₀). If Byte High Enable (BHE) is LOW, then data from I/O pins (I/O₈ through I/O₁₅) is written into the location specified on the address pins (A₀ through A₂₀).

Reading from the device is accomplished by taking Chip Enables (\overline{CE}_1 LOW and CE₂ HIGH) and Output Enable (\overline{OE}) LOW while forcing the Write Enable (WE) HIGH. If Byte Low Enable (BLE) is LOW, then data from the memory location specified by the address pins will appear on I/O₀ to I/O₇. If Byte High Enable (BHE) is LOW, then data from memory will appear on I/O₈ to I/O₁₅. See the truth table for a complete description of read and write modes.

Logic Block Diagram



Note

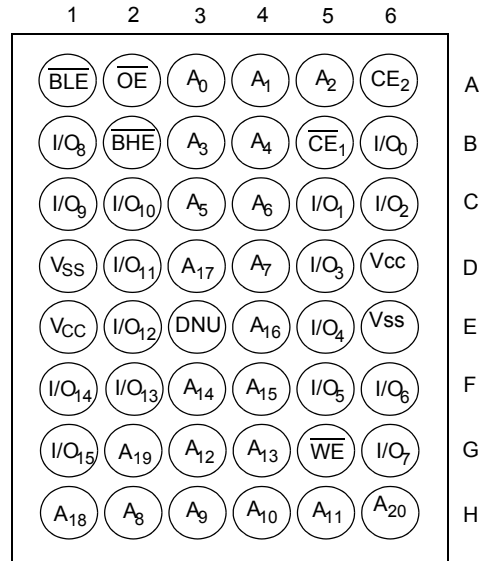
1. For best practice recommendations, please refer to the Cypress application note "System Design Guidelines" on <http://www.cypress.com>.

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Pin Configuration^[2]

Figure 1. 48-Ball FBGA Top View



Product Portfolio

Product	V _{CC} Range (V)			Speed (ns)	Power Dissipation					
					Operating I _{CC} (mA)				Standby I _{SB2} (μA)	
	f = 1 MHz		f = f _{max}							
	Min	Typ ^[3]	Max		Typ ^[3]	Max	Typ ^[3]	Max	Typ ^[3]	Max
CY62177DV30LL	2.2	3.0	3.6	55	2	4	15	30	5	50

Notes

- DNU pins have to be left floating or tied to V_{SS} to ensure proper application.
- Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at V_{CC} = V_{CC(typ.)}, T_A = 25 °C.

Maximum Ratings

(Exceeding maximum ratings may shorten the useful life of the device. User guidelines are not tested.)

Storage temperature -65 °C to + 150 °C
 Ambient temperature with power applied -55 °C to + 125 °C
 Supply voltage to ground potential -0.3 V to $V_{CC} + 0.3$ V
 DC voltage applied to outputs in High Z state^[4, 5] -0.3 V to $V_{CC} + 0.3$ V
 DC input voltage^[4, 5] -0.3 V to $V_{CC} + 0.3$ V

Output current into outputs (LOW) 20 mA
 Static discharge voltage >2001 V (per MIL-STD-883, method 3015)
 Latch-up current >200 mA

Operating Range

Device	Range	Ambient Temperature	V_{CC} ^[6]
CY62177DV30LL	Industrial	-40 °C to +85 °C	2.20 V to 3.60 V

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	Min	Typ ^[7]	Max	Unit	
V_{OH}	Output HIGH voltage	$I_{OH} = -0.1$ mA	$V_{CC} = 2.20$ V	2.0	–	–	V
		$I_{OH} = -1.0$ mA	$V_{CC} = 2.70$ V	2.4	–	–	V
V_{OL}	Output LOW voltage	$I_{OL} = 0.1$ mA	$V_{CC} = 2.20$ V	–	–	0.4	V
		$I_{OL} = 2.1$ mA	$V_{CC} = 2.70$ V	–	–	0.4	V
V_{IH}	Input HIGH voltage	$V_{CC} = 2.2$ V to 2.7 V	1.8	–	$V_{CC} + 0.3$ V	V	
		$V_{CC} = 2.7$ V to 3.6 V	2.2	–	$V_{CC} + 0.3$ V	V	
V_{IL}	Input LOW voltage	$V_{CC} = 2.2$ V to 2.7 V	-0.3	–	0.6	V	
		$V_{CC} = 2.7$ V to 3.6 V	-0.3	–	0.8	V	
I_{IX}	Input leakage current	$GND \leq V_I \leq V_{CC}$	-1	–	+1	μ A	
I_{OZ}	Output leakage current	$GND \leq V_O \leq V_{CC}$, output disabled	-1	–	+1	μ A	
I_{CC}	V_{CC} operating supply current	$f = f_{MAX} = 1/t_{RC}$	$V_{CC} = V_{CCmax}$ $I_{OUT} = 0$ mA CMOS levels	15	30	mA	
		$f = 1$ MHz		2	4	mA	
I_{SB1}	Automatic CE power-down current—CMOS inputs	$CE_1 \geq V_{CC} - 0.2$ V, $CE_2 < 0.2$ V, $V_{IN} \geq V_{CC} - 0.2$ V, $V_{IN} \leq 0.2$ V) $f = f_{MAX}$ (address and data only), $f = 0$ (OE, WE, BHE and BLE), $V_{CC} = 3.60$ V	–	5	100	μ A	
I_{SB2}	Automatic CE power-down current—CMOS inputs	$CE_1 \geq V_{CC} - 0.2$ V, $CE_2 < 0.2$ V, $V_{IN} \geq V_{CC} - 0.2$ V or $V_{IN} \leq 0.2$ V, $f = 0$, $V_{CC} = 3.60$ V	–	5	50	μ A	

Notes

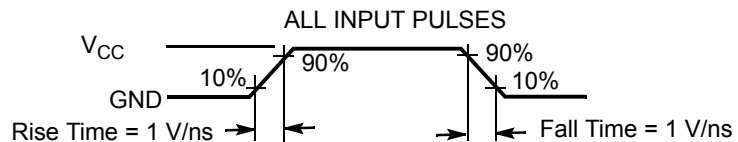
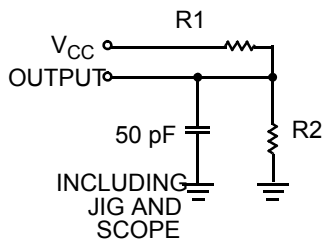
- $V_{IL(min)}$ = -2.0 V for pulse durations less than 20 ns.
- $V_{IH(Max)}$ = $V_{CC} + 0.75$ V for pulse durations less than 20 ns.
- Full Device AC operation requires linear V_{CC} ramp from 0 to $V_{CC(min)} \geq 500$ μ s.
- Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at $V_{CC} = V_{CC(typ)}$, $T_A = 25$ °C

Capacitance

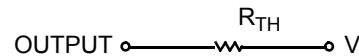
Parameter ^[8, 9]	Description	Test Conditions	Max.	Unit
C _{IN}	Input capacitance	T _A = 25 °C, f = 1 MHz, V _{CC} = V _{CC(typ)}	12	pF
C _{OUT}	Output capacitance		12	pF

Thermal Resistance

Parameter ^[9]	Description	Test Conditions	BGA	Unit
θ _{JA}	Thermal resistance (Junction to ambient)	Still Air, soldered on a 3 × 4.5 inch, two-layer printed circuit board	55	°C/W
θ _{JC}	Thermal resistance (Junction to case)		16	°C/W

AC Test Loads and Waveforms


Equivalent to: THÉVENIN EQUIVALENT



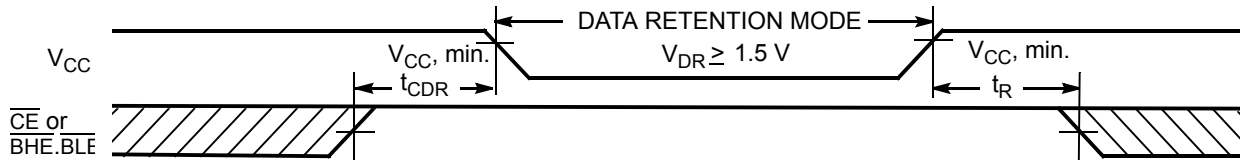
Parameters	2.5 V (2.2 V to 2.7 V)	3.0 V (2.7 V to 3.6 V)	Unit
R1	16667	1103	Ω
R2	15385	1554	Ω
R _{TH}	8000	645	Ω
V _{TH}	1.20	1.75	V

Data Retention Characteristics (Over the Operating Range)

Parameter	Description	Conditions	Min	Typ ^[10]	Max	Unit
V _{DR}	V _{CC} for data retention		1.5	–	–	V
I _{CCDR}	Data retention current	V _{CC} = 1.5 V CE ₁ ≥ V _{CC} - 0.2 V, CE ₂ < 0.2 V, V _{IN} ≥ V _{CC} - 0.2 V or V _{IN} ≤ 0.2 V	–		25	μA
t _{CDR} ^[9]	Chip deselect to data retention time		0	–	–	ns
t _R ^[11]	Operation recovery time		55	–	–	ns

Notes

8. This applies for all packages.
9. Tested initially and after any design or process changes that may affect these parameters.
10. Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at V_{CC} = V_{CC(typ)}, T_A = 25 °C
11. Full device operation requires linear V_{CC} ramp from V_{DR} to V_{CC(min)} ≥ 100 μs or stable at V_{CC(min)} ≥ 100 μs.

Data Retention Waveform^[12, 13]

Switching Characteristics Over the Operating Range

Parameter ^[13, 14]	Description	Min	Max	Unit
READ CYCLE				
t_{RC}	Read cycle time	55	–	ns
t_{AA}	Address to data valid	–	55	ns
t_{OHA}	Data hold from address change	10	–	ns
t_{ACE}	\overline{CE} LOW to data valid	–	55	ns
t_{DOE}	\overline{OE} LOW to data valid	–	25	ns
t_{LZOE}	\overline{OE} LOW to LOW Z ^[15]	5	–	ns
t_{HZOE}	\overline{OE} HIGH to High Z ^[15, 16]	–	20	ns
t_{LZCE}	\overline{CE} LOW to Low Z ^[15]	10	–	ns
t_{HZCE}	\overline{CE} HIGH to High Z ^[15, 16]	–	20	ns
t_{PU}	\overline{CE} LOW HIGH to power-up	0	–	ns
t_{PD}	\overline{CE} HIGH to power-down	–	55	ns
t_{DBE}	BLE/BHE LOW to data valid	–	55	ns
t_{LZBE}	$\overline{BLE}/\overline{BHE}$ LOW to Low Z ^[15]	10	–	ns
t_{HZBE}	$\overline{BLE}/\overline{BHE}$ HIGH to HIGH Z ^[15, 16]	–	20	ns
WRITE CYCLE^[17]				
t_{WC}	Write cycle time	55	–	ns
t_{SCE}	\overline{CE} LOW to write end	40	–	ns
t_{AW}	Address set-up to write end	40	–	ns
t_{HA}	Address hold from write end	0	–	ns
t_{SA}	Address set-up to write start	0	–	ns
t_{PWE}	\overline{WE} pulse width	40	–	ns
t_{BW}	$\overline{BLE}/\overline{BHE}$ LOW to write end	40	–	ns
t_{SD}	Data set-up to write end	25	–	ns
t_{HD}	Data hold from write end	0	–	ns
t_{HZWE}	\overline{WE} LOW to High Z ^[15, 16]	–	20	ns
t_{LZWE}	\overline{WE} HIGH to Low Z ^[15]	10	–	ns

Notes

12. $\overline{BHE.BLE}$ is the AND of both \overline{BHE} and \overline{BLE} . Chip can be deselected by either disabling the chip enable signals or by disabling both \overline{BHE} and \overline{BLE} .
13. CE is the logical combination of CE₁ and CE₂. When CE₁ is LOW and CE₂ is HIGH, CE is LOW; when CE₁ is HIGH or CE₂ is LOW, CE is HIGH.
14. Test conditions for all parameters other than tri-state parameters assume signal transition time of 1 ns/V, timing reference levels of $V_{CC(typ)}/2$, input pulse levels of 0 to $V_{CC(typ)}$, and output loading of the specified I_{OL}/I_{OH} as shown in the "AC Test Loads and Waveforms" section.
15. At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE} , t_{HZBE} is less than t_{LZBE} , t_{HZOE} is less than t_{LZOE} , and t_{HZWE} is less than t_{LZWE} for any given device.
16. t_{HZOE} , t_{HZCE} , t_{HZBE} , and t_{HZWE} transitions are measured when the outputs enter a high impedance state.
17. The internal Write time of the memory is defined by the overlap of \overline{WE} , $\overline{CE} = V_{IL}$, \overline{BHE} and/or $\overline{BLE} = V_{IL}$. All signals must be ACTIVE to initiate a write and any of these signals can terminate a write by going INACTIVE. The data input set-up and hold timing should be referenced to the edge of the signal that terminates the write.

Switching Waveforms

Figure 2. Read Cycle 1 (Address Transition Controlled)^[18, 19]

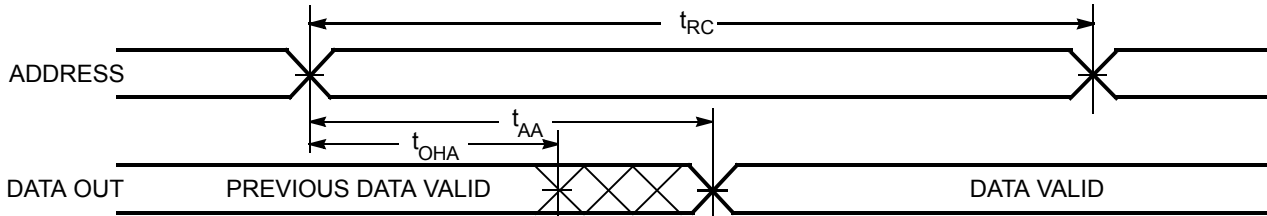
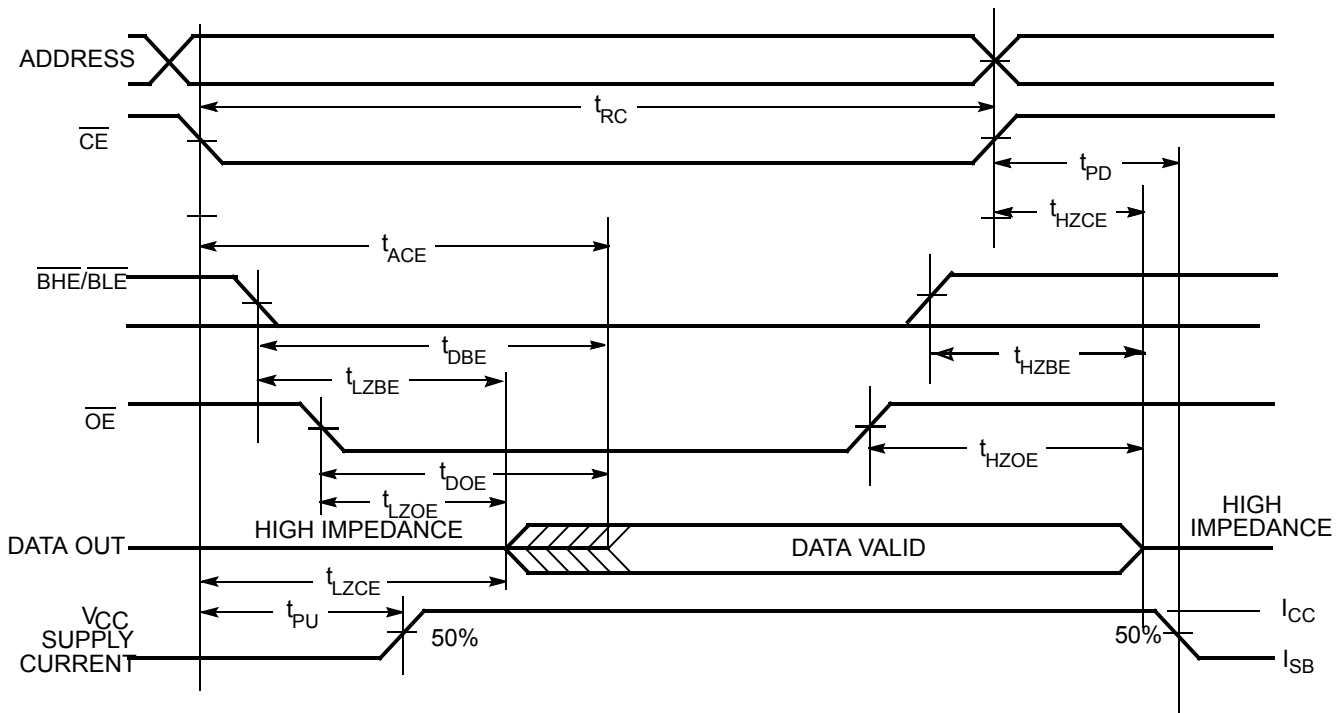


Figure 3. Read Cycle 2 (\overline{OE} Controlled)^[19, 20, 21]



Notes

- 18. The device is continuously selected. \overline{OE} , $\overline{CE} = V_{IL}$, \overline{BHE} and/or $\overline{BLE} = V_{IL}$.
- 19. \overline{WE} is HIGH for read cycle.
- 20. Address valid prior to or coincident with \overline{CE} , \overline{BHE} , \overline{BLE} transition LOW.
- 21. \overline{CE} is the logical combination of \overline{CE}_1 and CE_2 . When \overline{CE}_1 is LOW and CE_2 is HIGH, \overline{CE} is LOW; when \overline{CE}_1 is HIGH or CE_2 is LOW, \overline{CE} is HIGH.

Switching Waveforms (continued)

Figure 4. Write Cycle 1 (\overline{WE} Controlled)^[22, 23, 24, 25, 26]

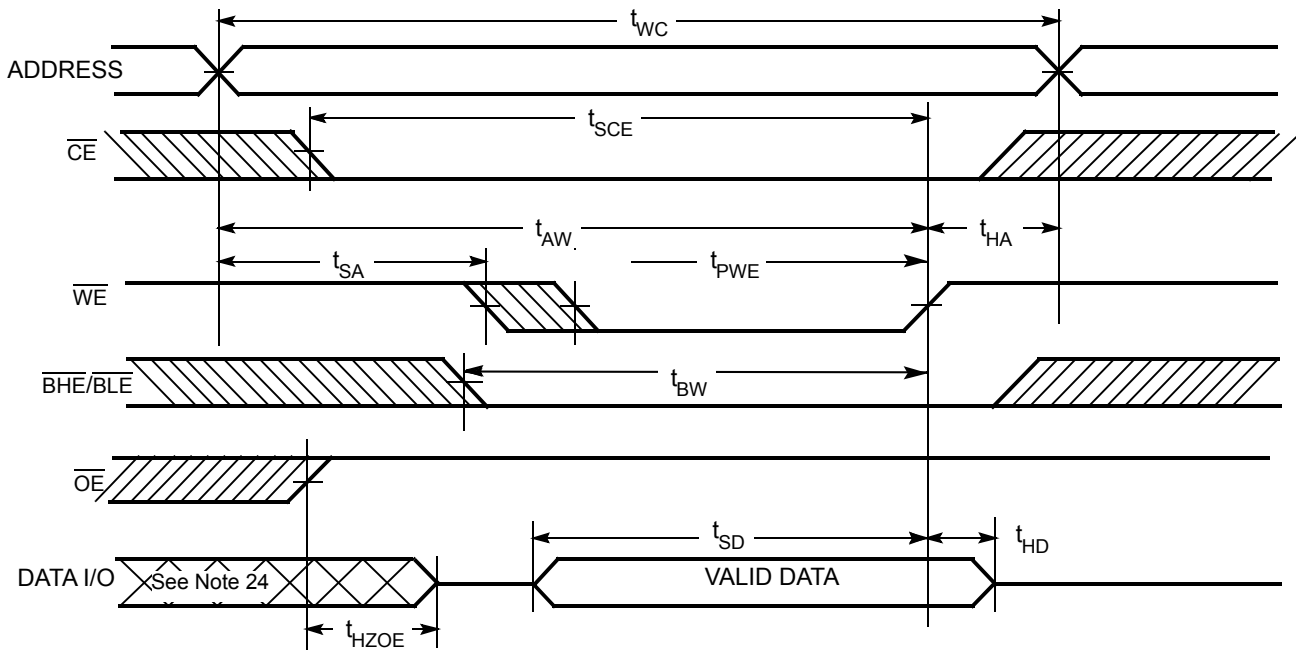
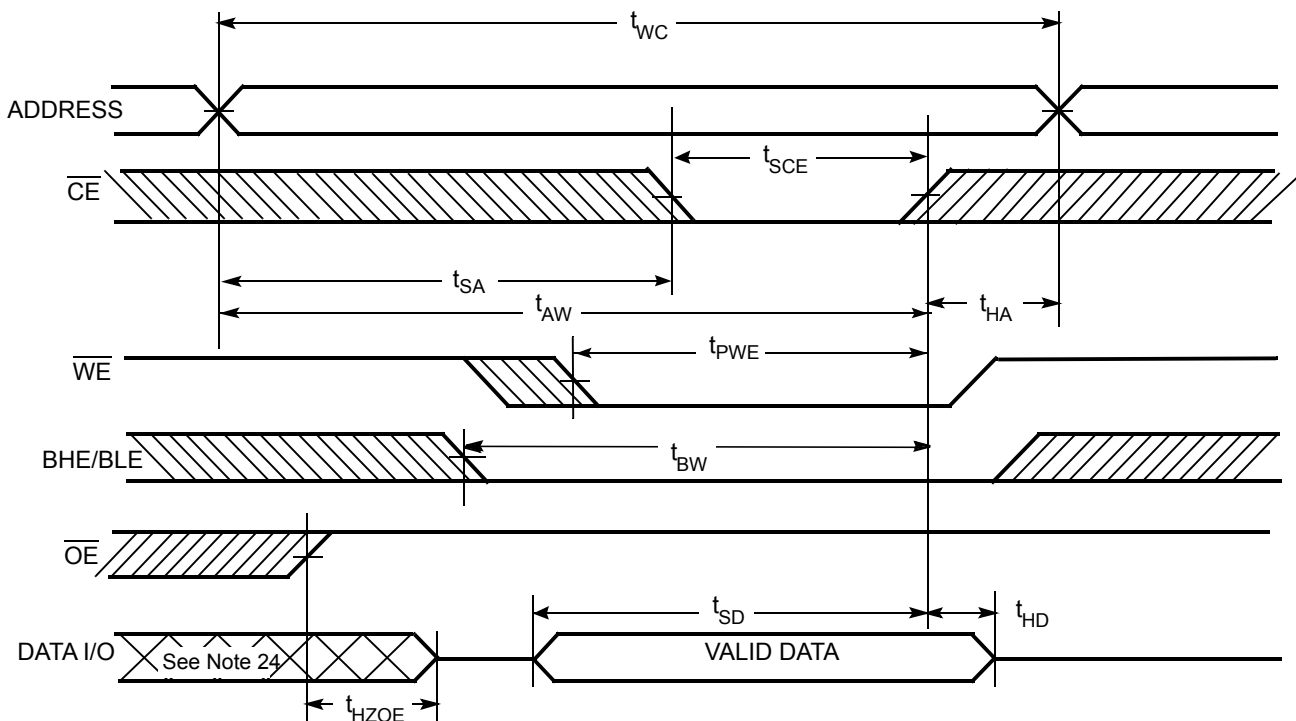


Figure 5. Write Cycle 2 (\overline{CE} Controlled)^[22, 23, 24, 25, 26]



Notes

- 22. Data I/O is high impedance if $\overline{OE} = V_{IH}$.
- 23. If \overline{CE} goes HIGH simultaneously with $\overline{WE} = V_{IH}$, the output remains in a high-impedance state.
- 24. During this period, the I/Os are in output state and input signals should not be applied.
- 25. \overline{CE} is the logical combination of \overline{CE}_1 and \overline{CE}_2 . When \overline{CE}_1 is LOW and \overline{CE}_2 is HIGH, \overline{CE} is LOW; when \overline{CE}_1 is HIGH or \overline{CE}_2 is LOW, \overline{CE} is HIGH.
- 26. The internal Write time of the memory is defined by the overlap of \overline{WE} , $\overline{CE} = V_{IL}$, \overline{BHE} and/or $\overline{BLE} = V_{IL}$. All signals must be ACTIVE to initiate a write and any of these signals can terminate a write by going INACTIVE. The data input set-up and hold timing should be referenced to the edge of the signal that terminates the write.

Switching Waveforms (continued)

Figure 6. Write Cycle 3 (\overline{WE} Controlled, \overline{OE} LOW)^[27, 28, 29]

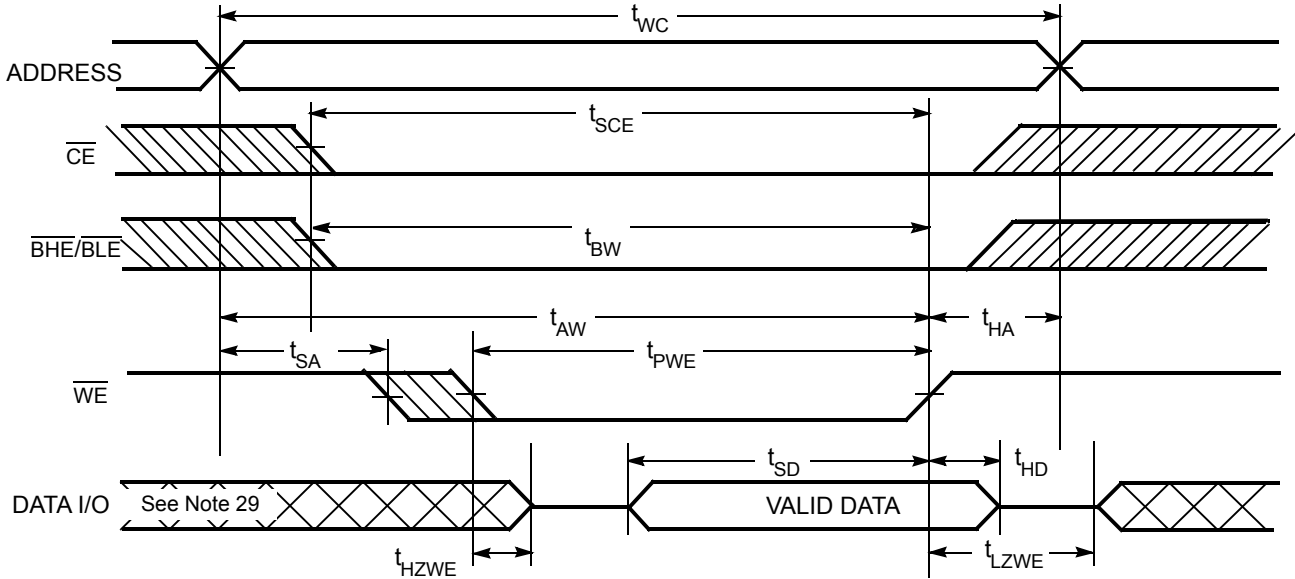
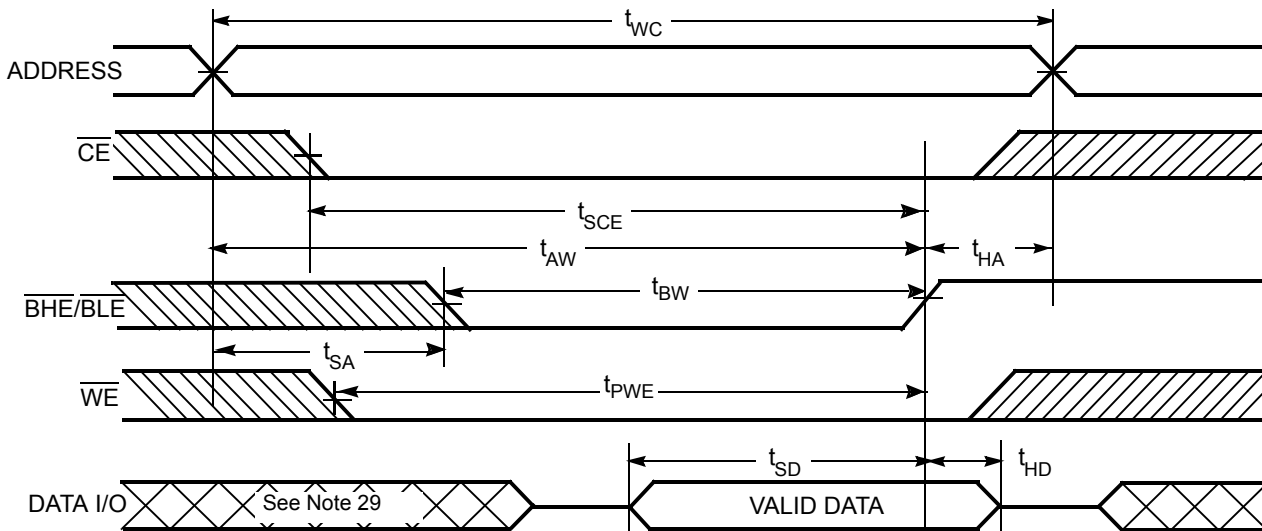


Figure 7. Write Cycle 4 ($\overline{BHE}/\overline{BLE}$ Controlled, \overline{OE} LOW)^[27, 28, 29]



Notes

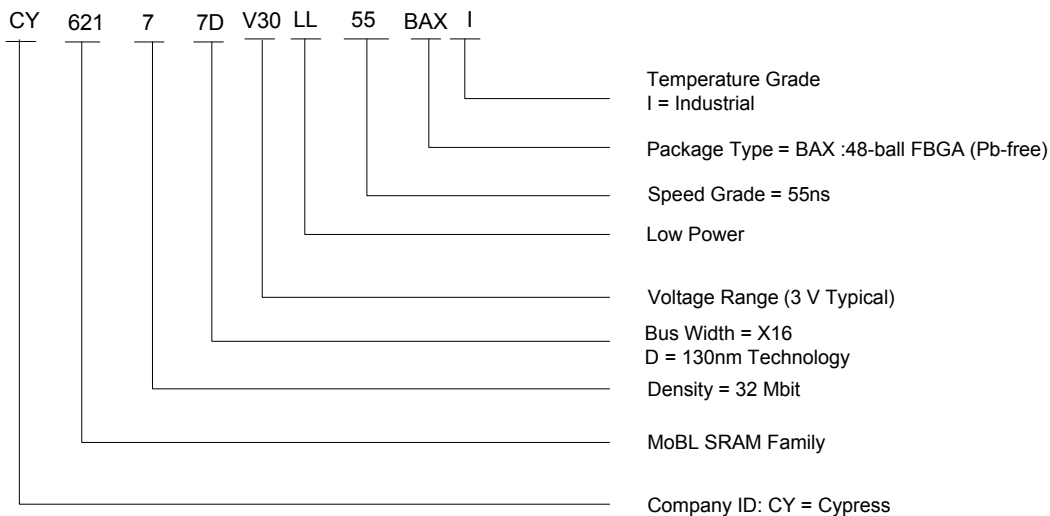
- 27. \overline{CE} is the logical combination of \overline{CE}_1 and CE_2 . When \overline{CE}_1 is LOW and CE_2 is HIGH, \overline{CE} is LOW; when \overline{CE}_1 is HIGH or CE_2 is LOW, \overline{CE} is HIGH.
- 28. If \overline{CE} goes HIGH simultaneously with $WE = \overline{V}_{IH}$, the output remains in a high-impedance state.
- 29. During this period, the I/Os are in output state and input signals should not be applied.

Truth Table

CE ₁	CE ₂	WE	OE	BHE	BLE	Inputs/Outputs	Mode	Power
H	X	X	X	X	X	High Z	Deselect/power-down	Standby (I _{SB})
X	L	X	X	X	X	High Z	Deselect/power-down	Standby (I _{SB})
X	X	X	X	H	H	High Z	Deselect/power-down	Standby (I _{SB})
L	H	H	L	L	L	Data out (I/O ₀ –I/O ₁₅)	Read	Active (I _{CC})
L	H	H	L	H	L	Data out (I/O ₀ –I/O ₇); High Z (I/O ₈ –I/O ₁₅)	Read	Active (I _{CC})
L	H	H	L	L	H	High Z (I/O ₀ –I/O ₇); Data Out (I/O ₈ –I/O ₁₅)	Read	Active (I _{CC})
L	H	H	H	L	H	High Z	Output disabled	Active (I _{CC})
L	H	H	H	H	L	High Z	Output disabled	Active (I _{CC})
L	H	H	H	L	L	High Z	Output disabled	Active (I _{CC})
L	H	L	X	L	L	Data in (I/O ₀ –I/O ₁₅)	Write	Active (I _{CC})
L	H	L	X	H	L	Data in (I/O ₀ –I/O ₇); High Z (I/O ₈ –I/O ₁₅)	Write	Active (I _{CC})
L	H	L	X	L	H	High Z (I/O ₀ –I/O ₇); Data in (I/O ₈ –I/O ₁₅)	Write	Active (I _{CC})

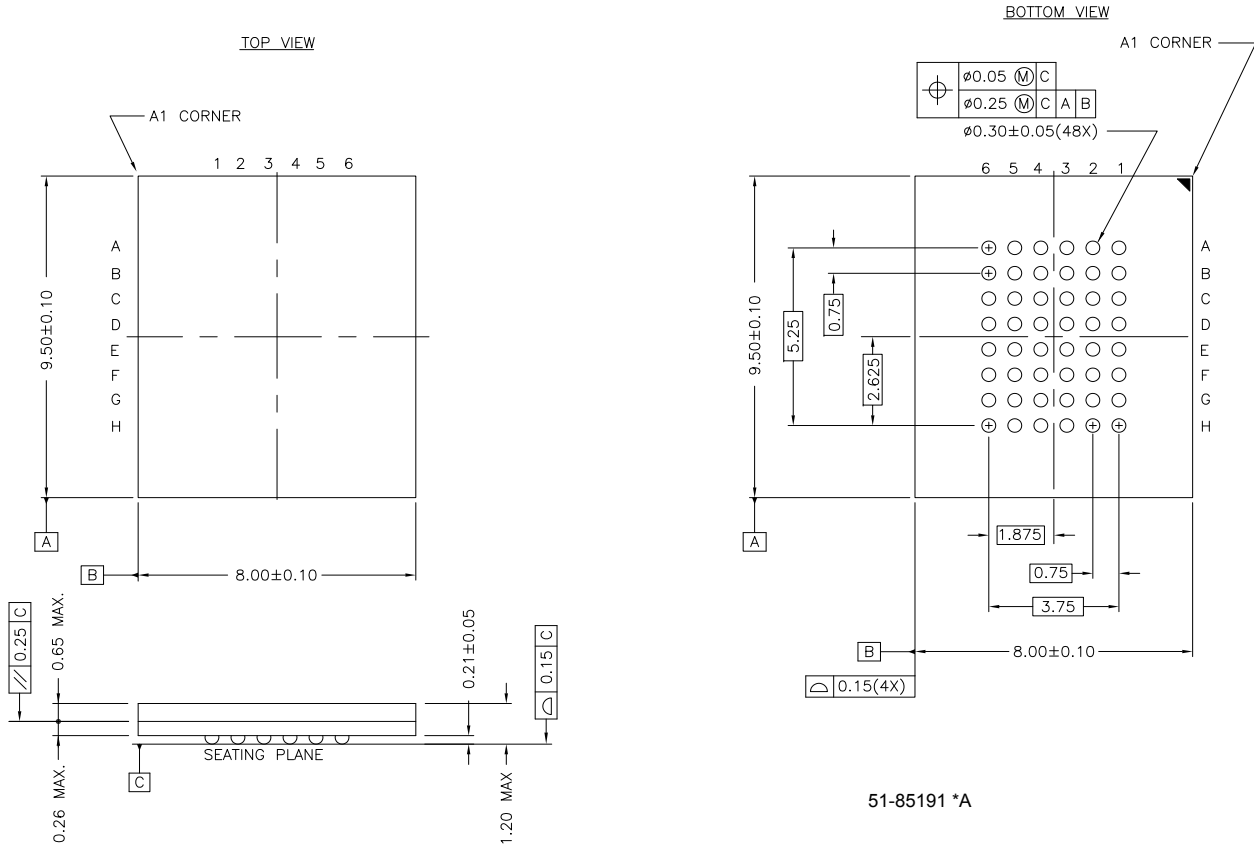
Ordering Information

Speed (ns)	Ordering Code	Package Diagram	Package Type	Operating Range
55	CY62177DV30LL-55BAXI	51-85191	48-ball FBGA (8 mm × 9.5mm × 1.2 mm) (Pb-free)	Industrial

Ordering Code Definition


Package Diagram

Figure 8. 48 ball FBGA (8 x 9.5 x 1.2 mm) (51-85191)



Acronyms

Acronym	Description
CMOS	complementary metal oxide semiconductor
I/O	input/output
SRAM	static random access memory
FBGA	fine ball grid array

Document Conventions

Units of Measure

Symbol	Unit of Measure
°C	degrees Celsius
μA	microamperes
mA	milliamperes
MHz	megahertz
ns	nanoseconds
pF	picofarads
V	volts
Ω	ohms
W	watts

Document History Page

Document Title: CY62177DV30 MoBL [®] 32-Mbit (2M x 16) Static RAM Document #: 38-05633				
REV.	ECN NO.	Issue Date	Orig. of Change	Description of Change
**	251075	See ECN	AJU	New Data Sheet
*A	330363	See ECN	AJU	Changed title of data sheet from CYM62177DV30 to CY62177DV30 Added second chip enable (CE ₂) Added footnote #12 on page 5
*B	400960	See ECN	NXR	Changed address of Cypress Semiconductor Corporation on Page# 1 from "3901 North First Street" to "198 Champion Court" Changed I _{SB1} from 60 and 40 μA to 100 μA for the L and LL versions for both the 55 and the 70 ns speed bins respectively.
*C	469187	See ECN	NXR	Converted from Preliminary to Final Changed the I _{SB2(Max)} from 40 μA to 50 μA for LL version of both 45 ns and 55 ns speed bins Changed the I _{CCDR(Max)} from 20 μA to 25 μA for LL version Updated the Ordering Information table
*D	2896036	03/19/10	AJU	Removed inactive parts from Ordering Information. Updated package diagram. Updated links in Sales, Solutions, and Legal Information.
*E	3153110	01/25/2011	RAME	Updated datasheet as per template Removed CY62177DV30L related info Removed 70 ns speed bin related info Added Ordering Code Definition Added Acronyms and Units of Measure table

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